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MOSFET - N-Channel, POWERTRENCH®

100 V, 40 A, 8.5 m Ω

FDPF085N10A

Description

This N-Channel MOSFET is Produced using **onsemi**'s advanced PowerTrench Process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Features

- $R_{DS(on)} = 6.5 \text{ m}\Omega \text{ (Typ.)} @ V_{GS} = 10 \text{ V}, I_D = 40 \text{ A}$
- Fast Switching Speed
- Low Gate Charge, Qg = 31 nC (Typ.)
- High Performance Trench Technology for Extremely Low R_{DS(on)}
- High Power and Current Handling Capability
- This Device is Pb-Free Halide, Free and RoHS Compliant

Applications

- Consumer Appliances
- LED TV
- Synchronous Rectification for ATX / Sever / Telecom PSU
- Motor Drives and Uninterruptible Power Supplies
- Micro Solar Inverter

ABSOLUTE MAXIMUM RATINGS

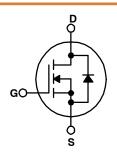
(T_C = 25°C unless otherwise noted.)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain to Source Voltage	100	V
V_{GSS}	Gate to Source Voltage	±20	V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C)	40 28	Α
I _{DM}	Drain Current - Pulsed (Note 1)	160	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	269	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	6.0	V/ns
P _D	P _D Power Dissipation - (T _C = 25°C) - Derate Above 25°C		W W/°C
T _J ,T _{STG}	C _J ,T _{STG} Operating and Storage Temperature Range		°C
TL	T _L Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



TO-220F CASE 221AT



MARKING DIAGRAM

FDPF08 5N10A AYWWZZ

FDPF085N10A = Specific Device Code
A = Assembly Location
YWW = Date Code (Year and Week)
ZZ = Assembly Lot Code

ORDERING INFORMATION

Device	Package	Shipping
FDPF085N10A	TO-220-3 FullPack	1000 Units / Tube

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Charac	teristics	•	_			-
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	0.07	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V	_	-	1	μΑ
		V _{DS} = 80 V, T _C = 150°C	_	-	500	
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	_	-	±100	nA
On Charac	teristics	•	_			-
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2.0	-	4.0	V
R _{DS(on)}	Static Drain to Source On-Resistance	V _{GS} = 10 V, I _D = 96 A	-	6.5	8.5	mΩ
9FS	Forward Transconductance	V _{DS} = 10 V, I _D = 96 A	-	76	-	S
Dynamic C	Characteristics					
C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	_	2025	2695	pF
Coss	Output Capacitance		-	468	620	pF
C _{rss}	Reverse Transfer Capacitance	7	-	20	-	pF
C _{oss} (er)	Engry Related Output Capacitance	V _{DS} = 50 V, V _{GS} = 0 V	-	752	-	pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{GS} = 10 V, V _{DS} = 50 V, I _D = 96 A	-	31	40	nC
Q _{gs}	Gate to Source Gate Charge	(Note 4)	-	9.7	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau	1	-	5.0	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	1	-	7.5	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	_	0.97	-	Ω
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 50 V, I _D = 96 A,	-	18	46	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_G = 4.7 \Omega \text{ (Note 4)}$	-	22	54	ns
t _{d(off)}	Turn-Off Delay Time	1	-	29	68	ns
t _f	Turn-Off Fall Time		-	8	26	ns
Drain-Sou	rce Diode Characteristics and Maximum F	Ratings				
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	40	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		_	_	160	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 96 A	-	_	1.3	V
t _{rr}	Reverse Recovery Time	V _{DD} = 50 V, V _{GS} = 0 V, I _{SD} = 96 A,	-	59	-	ns
Q _{rr}	Reverse Recovery Charge	dl _F /dt = 100 A/μs	_	80	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 1. Repetitive Rating: Pulse-width limited by maximum junction temperature.
- 2. L = 3 mH, I_{AS} = 13.4 A, R_G = 25 Ω starting T_J = 25°C. 3. I_{SD} ≤ 40 A, di/dt ≤ 200 A/ μ s, V_{DD} ≤ BV_{DSS}, starting T_J = 25°C. 4. Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS

_D, Drain Current (A)

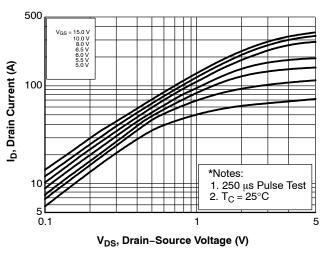


Figure 1. On-Region Characteristics

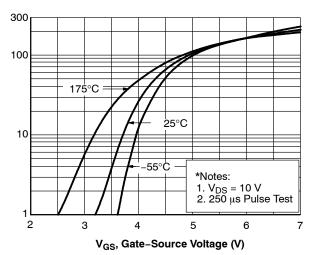


Figure 2. Transfer Characteristics

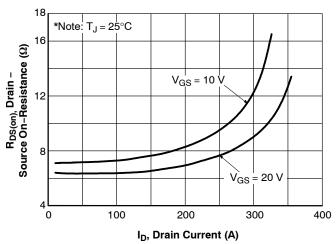


Figure 3. On–Resistance Variation vs Drain Current and Gate Voltage

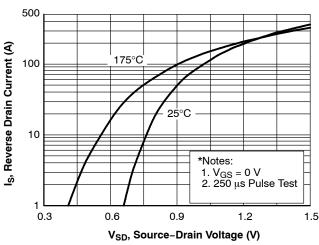


Figure 4. Body Diode Forward Voltage Variation vs Source Current and Temperature

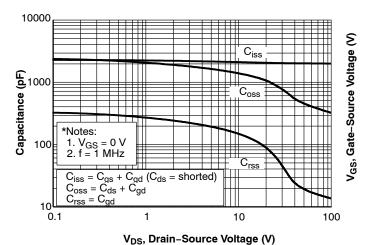


Figure 5. Capacitance Characteristics

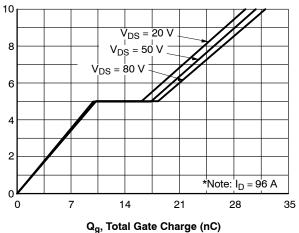
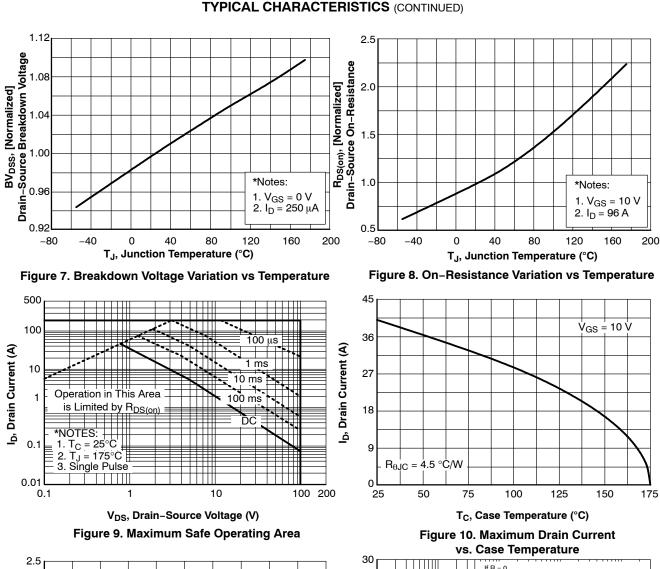


Figure 6. Gate Charge Characteristics



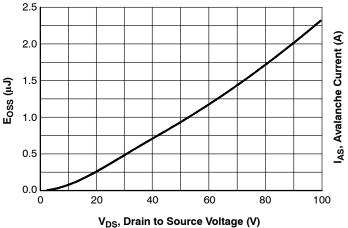
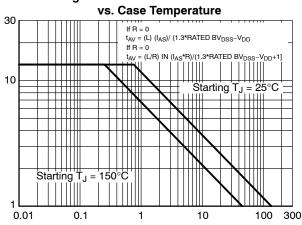


Figure 11. Eoss vs. Drain to Source Voltage



t_{AV}, Time in Avalanche (ms)
Figure 12. Unclamped Inductive
Switching Capability

TYPICAL CHARACTERISTICS (CONTINUED)

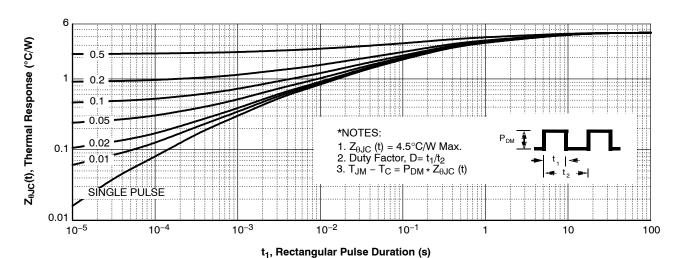


Figure 13. Transient Thermal Response Curve

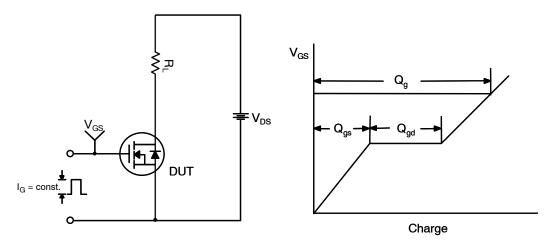


Figure 14. Gate Charge Test Circuit & Waveform

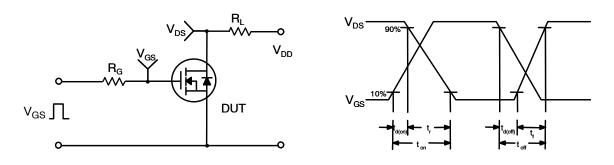


Figure 15. Resistive Switching Test Circuit & Waveforms

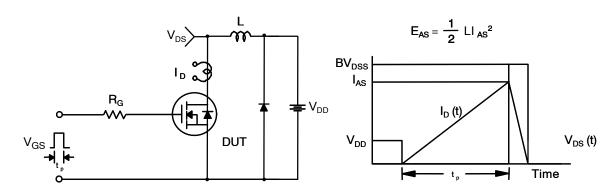
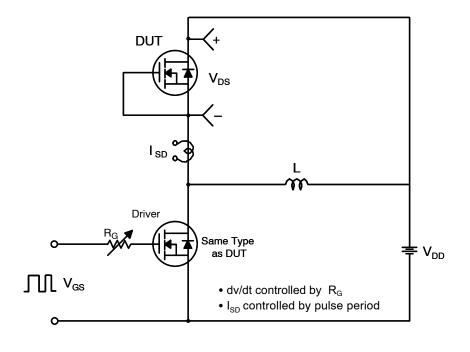


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms



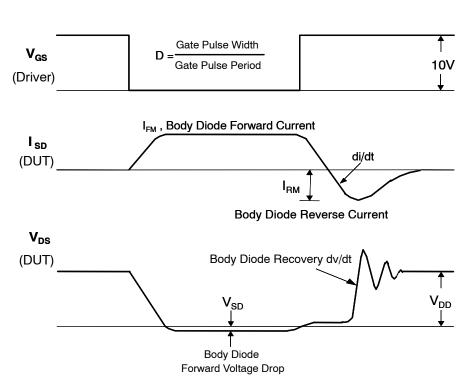
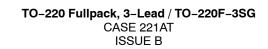
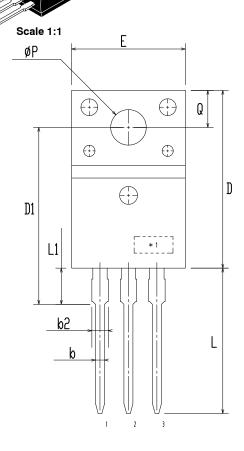
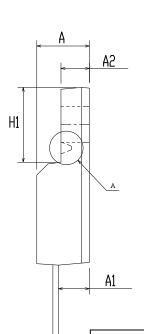


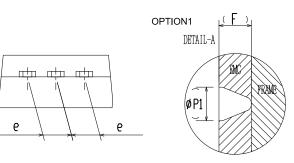
Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms



DATE 19 JAN 2021







DIM	MILLIMITERS .			
ויונע	MIN	NDM	MAX	
Α	4.50	4.70	4.90	
A1	2.56	2.76	2.96	
A2	2.34	2.54	2.74	
b	0.70	0.80	0.90	
b2	~	2	1.47	
С	0.45	0.50	0.60	
D	15.67	15.87	16.07	
D1	15.60	15.80	16.00	
E	9.96	10.16	10.36	
е	2.34	2.54	2.74	
F	~	0.84	2	
H1	6.48	6.68	6.88	
L	12.78	12.98	13.18	
L1	3.03	3.23	3.43	
ØΡ	2.98	3.18	3.38	
Ø P1	~	1.00	~	
Q	3.20	3.30	3,40	

MILLIMITEDS

NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.

C

C. OPTION 1 - WITH SUPPORT PIN HOLE OPTION 2 - NO SUPPORT PIN HOLE

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